



News Release

Unisem Reports Revenue of RM282.9 million Resulting in Net income of RM8.3 million for Third Quarter 2012

Kuala Lumpur, 8 November 2012 – Unisem (M) Berhad today announced results for the third quarter ended 30 September 2012 (**3Q12**).

Unisem recorded a consolidated revenue of RM282.9 million (approx. US\$90.4 million) for 3Q12, which represents 0% change from the preceding quarter (**2Q12**) and decline of 1.8 percent compared to revenue recorded in the same quarter a year ago (**3Q11**). The Group recorded a consolidated net income of RM8.3 million (approx. US\$2.7 million) compared to net loss of RM7.8 million (approx. US\$2.5 million) in 2Q12 and net income of RM4.9 million (approx. US\$1.6 million) in 3Q11. The improve in the consolidated net income was mainly attributable to improved profit margins due to changes in product mix as well as higher gains on foreign exchange.

Group earnings before interest, tax, depreciation and amortization (**EBITDA**) for 3Q12 came in at about RM54.0 million (approx. US\$17.2 million), EBITDA margin was about 19 percent, an increase of 36 percent from 2Q12. Equipment capacity utilization averaged at about 67 percent for the group in 3Q12. Group capital expenditure incurred in 3Q12 was about RM48.8 million (approx. US\$15.6 million), principally for purchase of equipment for advanced packaging activities for Unisem (M) Berhad and Unisem Chengdu.

Commenting on the outlook of the Group, Mr. John Chia Sin Tet, group managing director said, "The operating environment remains challenging due to the prevailing global economic conditions. As we approach the financial year end we also expect a subdued fourth quarter due to seasonal inventory adjustments. The implementation of our new business model (essentially rationalising our package portfolio and customer profile) is in progress and we expect it to yield favourable results in the coming quarters."

About Unisem

Unisem is a global provider of semiconductor assembly and test services for many of the world's most successful electronics companies. Unisem offers an integrated suite of packaging and test services such as wafer bumping, wafer probing, wafer grinding, a wide range of leadframe and substrate IC packaging, wafer level CSP and RF, analog, digital and mixed-signal test services. Our turnkey services include design, assembly, test, failure analysis, and electrical and thermal characterization. With approximately 8,500 employees worldwide, Unisem has factory locations in Ipoh, Malaysia; Wales, United Kingdom; Chengdu, People's Republic of China; Batam, Indonesia and Sunnyvale, USA. The company is headquartered in Kuala Lumpur, Malaysia. For more information about the company, its products and services, please visit its website at www.unisemgroup.com.

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